AMENDMENTS TO THE CLAIMS

IN THE CLAIMS:

Please amend Claims 1 and 27 such that the claims read as follows:

Claim 1 (currently amended): Support apparatus for an installation of semiconductor processing equipment having a bottom outline and a plurality of load-bearing mounting feet disposed along the equipment's bottom outline, the support apparatus comprising:

a plurality of support legs; and

a non-rectangular frame disposed on the plurality of support legs, the frame having a frame outline which is adapted to substantially duplicate the bottom outline of the semiconductor processing equipment, the frame being configured to:

support the installation of semiconductor processing equipment by aligning with the plurality of load-bearing mounting feet of the semiconductor processing equipment; and

provide one or more facilities connection locations that are adapted to be pre-aligned to one or more facilities connection points of the semiconductor processing equipment and that are positioned outside of a periphery of the non-rectangular frame, the one or more facilities connection locations adapted to pre-align at least one of a vacuum line, a gas supply line and a fluid supply line to the semiconductor processing equipment prior to installation of the semiconductor processing equipment.

Claim 2 (original): The support apparatus of Claim 1 wherein each of the plurality of support legs is adapted to extend down to a base mount location on underlying flooring.

Claim 3 (previously presented): The support apparatus of Claim 2 wherein the underlying flooring comprises a waffle-grid floor and wherein each base mount location comprises a pad adapted to be disposed at an interstice of the waffle-grid floor.

Claim 4 (original): The support apparatus of Claim 1 wherein the frame comprises a monolithic frame.

Claim 5 (original): The support apparatus of Claim 4 wherein the monolithic frame comprises a molded steel frame.

Claim 6 (original): The support apparatus of Claim 1 wherein each of the plurality of support legs comprises an adjustable length leg.

Claim 7 (original): The support apparatus of Claim 1 further comprising flanges about the periphery of the frame for supporting raised flooring.

Claim 8 (previously presented): The support apparatus of Claim 1 further comprising flanges along inner edges of the frame to support raised flooring.

Claim 9 (previously presented): The support apparatus of Claim 7 further comprising flanges along inner edges of the frame to support raised flooring.

Claim 10 (original): The support apparatus of Claim 1 further comprising at least one facilities connection locator integrated into the periphery of the frame.

Claim 11 (previously presented): The support apparatus of Claim 10 wherein the at least one facilities connection locator provides a plurality of connection points adapted for connecting site facilities to the semiconductor processing equipment.

Claim 12 (original): The support apparatus of Claim 11 further comprising gooseneck couplings attached at the plurality of connection points.

Claim 13 (previously presented): The support apparatus of Claim 1 further comprising a plurality of seismic braces each affixed to one of the support legs and adapted to fix to a piece of semiconductor processing equipment to be supported by the support apparatus.

Claims 14-26 (canceled).

Claim 27 (currently amended): Support apparatus for an installation of semiconductor processing equipment having a bottom outline and a plurality of load-bearing mounting feet disposed along the equipment's bottom outline, the support apparatus comprising:

a frame adapted to be disposed on a plurality of support legs, the frame having a frame outline which is adapted to substantially duplicate the bottom outline of the semiconductor processing equipment, the frame being configured to provide one or more facilities connection locations that are adapted to be pre-aligned to one or more

facilities connection points of the semiconductor processing equipment and that are positioned outside of a periphery of the frame.

Claim 28 (previously presented): The support apparatus of Claim 27 further comprising a plurality of support legs, wherein each of the plurality of support legs is adapted to extend down to a base mount location on underlying flooring.

Claim 29 (previously presented): The support apparatus of Claim 28 wherein the underlying flooring comprises a waffle-grid floor and wherein each base mount location comprises a pad adapted to be disposed at an interstice of the waffle-grid floor.

Claim 30 (previously presented): The support apparatus of Claim 27 wherein the frame comprises a monolithic frame.

Claim 31 (previously presented): The support apparatus of Claim 30 wherein the monolithic frame comprises a molded steel frame.

Claim 32 (previously presented): The support apparatus of Claim 27 further comprising a plurality of support legs, wherein each of the plurality of support legs comprises an adjustable length leg.

Claim 33 (previously presented): The support apparatus of Claim 27 further comprising flanges about the periphery of the frame for supporting raised flooring.

Claim 34 (previously presented): The support apparatus of Claim 27 further comprising flanges along inner edges of the frame to support raised flooring.

Claim 35 (previously presented): The support apparatus of Claim 33 further comprising flanges along inner edges of the frame to support raised flooring.

Claim 36 (previously presented): The support apparatus of Claim 27 further comprising at least one facilities connection locator integrated into the periphery of the frame.

Claim 37 (previously presented): The support apparatus of Claim 36 wherein the at least one facilities connection locator provides a plurality of connection points adapted for connecting site facilities to the semiconductor processing equipment.

Claim 38 (previously presented): The support apparatus of Claim 37 further comprising gooseneck couplings attached at the plurality of connection points.

Claim 39 (previously presented): The support apparatus of Claim 27 further comprising:

a plurality of support legs; and

a plurality of seismic braces each affixed to one of the support legs and adapted to fix to a piece of semiconductor processing equipment to be supported by the support apparatus.